

## SPECIFICATION AMENDMENTS

On page 1, please correct the section entitled: Cross-Reference to Related Applications (paragraph [0001]), as follows:

-- This application is a continuation of International Application PCT/IB2003/004143 [[PCT/FR03/02577]] filed August 26, 2003, and claims the benefit of U.S. provisional application no. 60/431,928 filed December 9, 2002.--.

On page 7, the 4th paragraph (paragraph [0036]) is revised to read:

-- FIGs. 7a to 7f illustrate [[shows]] the various steps of a method according to the invention successively comprising detachment of a thin layer from a donor wafer and recycling of the donor wafer after detachment.--.